

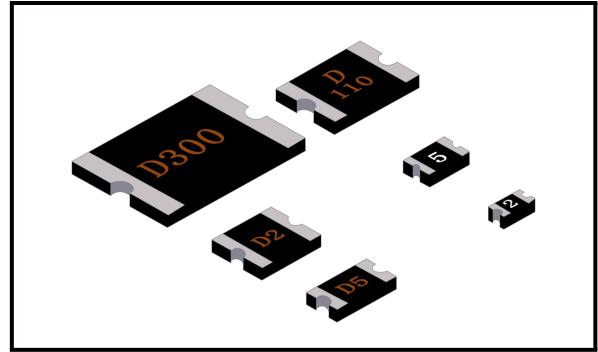
BxSMHxx Series

High Temperature Series
Surface Mount PPTC Devices

Features

- High operating temperature -40°C~125°C
- Compact design saves board space
- RoHS compliant,halogen-free and lead-free
- Resettable solution against overcurrent and short circuit
- Fast response to fault current
- Symmetrical design
- HF、RoHS、REACH、Pb Free

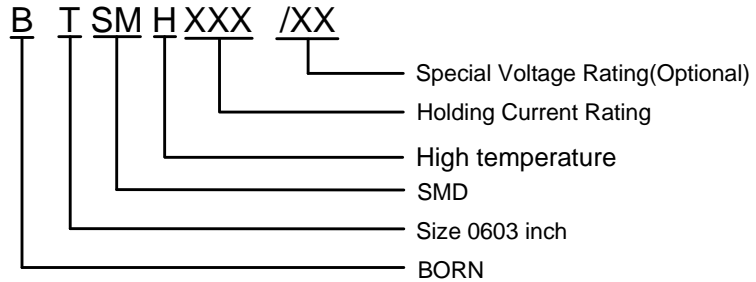
Package



Applications

- Automotive and Industrial Transport
- Frequency Converter
- Sensor Protection
- Infotainment/Telematic
- Outdoor Electronic Equipment
- Climate Control Systems
- Security and Communication Systems

Part Numbering



Environmental Specifications

Operating Temperature	-40°C to +125 °C
Passive Aging	+85°C, 1000 hours; R≤ R1max
Humidity Aging	+85°C, 85% R.H.100 hours; R≤ R1max
Thermal Shock	MIL-STD-202, Method 107; +125°C to -40°C, 1 times; R≤ R1max
Solvent Resistance	MIL-STD-202, Method 215; No change
Vibration	MIL-STD-883, Method 2007, Condition A; No change
Moisture Sensivity Level	Level 1, J-STD-020
Storage Conditions	+40°C Max.70% RH Max. Packed in original packaging.



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Electrical Characteristics

Part Number	V_{max}	I_{max}	I_{hold}	I_{trip}	$P_{dtyp.}$	Maximum Time To Trip		$R0min$	$R1max$	Package
	(A)	(A)	(V _{dc})	(A)	(W)	Current(A)	Time(Sec.)	(Ω)	(Ω)	
BTSMH010/24	24	40	0.1	0.5	0.5	2.5	1.5	0.9	8.5	0603
BTSMH016/24	24	40	0.16	0.48	0.5	8	0.1	0.6	6	0603
BTSMH020/16	16	40	0.2	0.6	0.6	8	0.5	0.35	4.5	0603
BTSMH035/16	16	40	0.35	1.05	0.6	8	0.5	0.3	4	0603
BISMH010/24	24	40	0.1	0.5	0.9	2.5	1.5	0.8	6.5	0805
BISMH020/24	24	40	0.2	0.6	0.9	8	0.1	0.45	5	0805
BISMH035/16	16	40	0.35	1.05	0.9	8	0.1	0.3	1.9	0805
BISMH050/16	16	40	0.5	1.5	0.9	8	0.1	0.25	1.6	0805
BISMH075/16	16	40	0.75	2.25	0.9	8	1	0.13	1.2	0805
BNSMH016/30	30	20	0.16	0.8	1	8	0.1	0.4	6	1206
BNSMH020/30	30	20	0.2	1	1	8	0.1	0.35	5	1206
BNSMH035/24	24	40	0.35	1.05	1	8	0.1	0.2	1.6	1206
BNSMH050/16	16	40	0.5	1.5	1	8	0.1	0.14	1.2	1206
BNSMH050/24	24	40	0.5	1.5	1.2	8	0.1	0.14	1.2	1206
BNSMH075/16	16	40	0.75	2.25	1	8	5	0.08	0.7	1206
BNSMH075/24	24	40	0.75	2.25	1.2	8	0.5	0.08	0.7	1206
BNSMH110/16	16	40	1.1	3.3	1	8	5	0.06	0.45	1206
BNSMH125/16	16	40	1.25	3.75	1	8	5	0.05	0.35	1206
BFSMH110/16	16	40	1.1	3.3	1.5	8	5	0.06	0.5	1210
BFSMH125/16	16	40	1.25	3.75	1.5	8	4	0.03	0.3	1210
BFSMH150/16	16	40	1.5	4.5	1.5	8	5	0.025	0.25	1210
BFSMH175/16	16	40	1.75	5.25	1.5	8	5	0.02	0.2	1210
BMSMH050/30	30	40	0.5	1.5	1.2	8	0.1	0.12	1.2	1812
BMSMH075/30	30	40	0.75	2.25	1.5	8	5	0.09	0.75	1812
BMSMH110/24	24	40	1.1	3.3	1.5	8	5	0.038	0.35	1812
BMSMH125/24	24	40	1.25	3.75	1.5	8	5	0.03	0.3	1812
BMSMH150/24	24	40	1.5	4.5	1.5	8	5	0.022	0.2	1812
BMSMH150/33	33	40	1.5	4.5	1.5	8	5	0.022	0.2	1812
BMSMH175/24	24	40	1.75	5.25	1.5	8	5	0.018	0.17	1812
BMSMH200/24	24	40	2	6	1.5	10	5	0.015	0.12	1812
BMSMH200/30	30	40	2	6	1.5	8	5	0.015	0.12	1812
BMSMH250/24	24	40	2.5	7.5	1.5	12.5	5	0.013	0.09	1812



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Electrical Characteristics

Part Number	V_{max}	I_{max}	I_{hold}	I_{trip}	$P_{dtyp.}$	Maximum Time To Trip		R_{0min}	R_{1max}	Package
	(A)	(A)	(V _{dc})	(A)	(W)	Current(A)	Time(Sec.)	(Ω)	(Ω)	
BSMH260/24	24	40	2.6	7.8	3	13	5	0.007	0.065	2920
BSMH300/24	24	40	3	9	3	15	5	0.006	0.055	2920
BSMH330/24	24	40	3.3	9.9	3	16.5	5	0.005	0.045	2920
BSMH350/24	24	40	3.5	10.5	3	17	5	0.005	0.04	2920
BSMH400/24	24	40	4	12	3	20	5	0.004	0.035	2920

V_{max} : Maximum operating voltage device can withstand without damage at rated current(I_{max}).

I_{max} : Maximum fault current device can withstand without damage at rated voltage(V_{max}).

I_{hold} : Holding Current: maximum current device will not trip in 25°C still air.

I_{trip} : Tripping Current: minimum current at which the device will always trip in 25° still air.

$P_{dtyp.}$: Power dissipated when device is in the tripped state at 25°C still air environment at rated voltage.

R_{0min} : Minimum resistance of device in initial (un-soldered) state.

R_{1max} : Maximum resistance of device at 25°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

Test Procedures And Requirements

Test	Test Conditions	Accept/Reject Criteria
R0 min	Resistance measurement at 25°C	$R_{0min} \leq R \leq R_{1max}$
R1 max	Resistance measurement one hour after post trip	$R_{0min} \leq R \leq R_{1max}$
I-hold	Hold rated current 1800 second without trip, @25°C	No trip
I-trip	Device must trip within 900 second under rated current, @25°C	Trip
Max. time to trip	At specified current, 25°C	$T \leq \text{max. time to trip (seconds)}$
Trip Cycle Life	V_{max} , I_{max} , 100 cycles	No arcing or burning
Trip Endurance	V_{max} , I_{max} 24 hours	No arcing or burning
Solderability	ANSI/J-STD-002	95 % min. coverage

Thermal Derating Chart(Recommended Hold Current(A) at Ambient Temperature(°C))

Part Number	Ambient Operating Temperature									
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C	125°C
BTSMH010/24	0.15	0.13	0.12	0.1	0.09	0.08	0.07	0.07	0.06	0.03
BTSMH016/24	0.23	0.21	0.19	0.16	0.14	0.13	0.12	0.11	0.09	0.04
BTSMH020/16	0.29	0.26	0.23	0.2	0.18	0.16	0.15	0.13	0.11	0.05
BTSMH035/16	0.51	0.46	0.41	0.35	0.31	0.28	0.26	0.23	0.2	0.09
BISMH010/24	0.15	0.13	0.12	0.1	0.09	0.08	0.07	0.07	0.06	0.03
BISMH020/24	0.29	0.26	0.23	0.2	0.18	0.16	0.15	0.13	0.11	0.05
BISMH035/16	0.51	0.46	0.41	0.35	0.31	0.28	0.26	0.23	0.2	0.09

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Specifications are subject to change without notice.

Please refer to <http://www.born-tw.com> for current information.

Revision: 2022-Jan-1-A



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Thermal Derating Chart(Recommended Hold Current(A) at Ambient Temperature(°C))

Part Number	Ambient Operating Temperature									
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C	125°C
BISMH050/16	0.73	0.65	0.58	0.5	0.44	0.41	0.37	0.33	0.28	0.13
BISMH075/16	1.09	0.98	0.87	0.75	0.66	0.61	0.56	0.5	0.42	0.2
BNSMH016/30	0.23	0.21	0.19	0.16	0.14	0.13	0.12	0.11	0.09	0.04
BNSMH020/30	0.29	0.26	0.23	0.2	0.18	0.16	0.15	0.13	0.11	0.05
BNSMH035/24	0.51	0.46	0.41	0.35	0.31	0.28	0.26	0.23	0.2	0.09
BNSMH050/16	0.73	0.65	0.58	0.5	0.44	0.41	0.37	0.34	0.28	0.14
BNSMH050/24	0.73	0.65	0.58	0.5	0.44	0.41	0.37	0.34	0.28	0.14
BNSMH075/16	1.09	0.98	0.87	0.75	0.66	0.61	0.56	0.5	0.42	0.2
BNSMH075/24	1.09	0.98	0.87	0.75	0.66	0.61	0.56	0.5	0.42	0.2
BNSMH110/16	1.6	1.44	1.28	1.1	0.97	0.89	0.82	0.74	0.62	0.3
BNSMH125/16	1.81	1.64	1.45	1.25	1.1	1.01	0.93	0.84	0.7	0.34
BFSMH110/16	1.6	1.44	1.16	1.1	0.97	0.89	0.82	0.74	0.62	0.3
BFSMH125/16	1.81	1.64	1.45	1.25	1.1	1.01	0.93	0.84	0.7	0.34
BFSMH150/16	2.18	1.96	1.74	1.5	1.32	1.22	1.11	1	0.84	0.4
BFSMH175/16	2.54	2.29	2.03	1.75	1.54	1.42	1.3	1.17	0.98	0.47
BMSMH050/30	0.73	0.65	0.58	0.5	0.44	0.41	0.37	0.33	0.28	0.13
BMSMH075/30	1.09	0.98	0.87	0.75	0.66	0.61	0.56	0.5	0.42	0.2
BMSMH110/24	1.6	1.44	1.28	1.1	0.97	0.89	0.82	0.74	0.62	0.3
BMSMH125/24	1.81	1.64	1.45	1.25	1.1	1.01	0.93	0.84	0.7	0.34
BMSMH150/24	2.18	1.96	1.74	1.5	1.32	1.22	1.11	1	0.84	0.4
BMSMH150/33	2.18	1.96	1.74	1.5	1.32	1.22	1.11	1	0.84	0.4
BMSMH175/24	2.54	2.29	2.03	1.75	1.54	1.42	1.3	1.17	0.98	0.47
BMSMH200/24	2.9	2.62	2.32	2	1.76	1.62	1.49	1.34	1.12	0.54
BMSMH200/30	2.9	2.62	2.32	2	1.76	1.62	1.49	1.34	1.12	0.54
BMSMH250/24	3.63	3.27	2.9	2.5	2.2	2.03	1.86	1.67	1.4	0.67
BSMH260/24	3.77	3.4	3.02	2.6	2.29	2.11	1.93	1.74	1.46	0.7
BSMH300/24	4.35	3.93	3.48	3	2.64	2.43	2.23	2.01	1.68	0.81
BSMH330/24	4.79	4.32	3.83	3.3	2.9	2.68	2.45	2.21	1.85	0.89
BSMH350/24	5.08	4.58	4.06	3.5	3.08	2.84	2.6	2.34	1.96	0.94
BSMH400/24	5.81	5.23	4.64	4	3.52	3.25	2.97	2.67	2.24	1.07



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Typical time to trip at 25°C

Figure 1: 0603&0805 Series

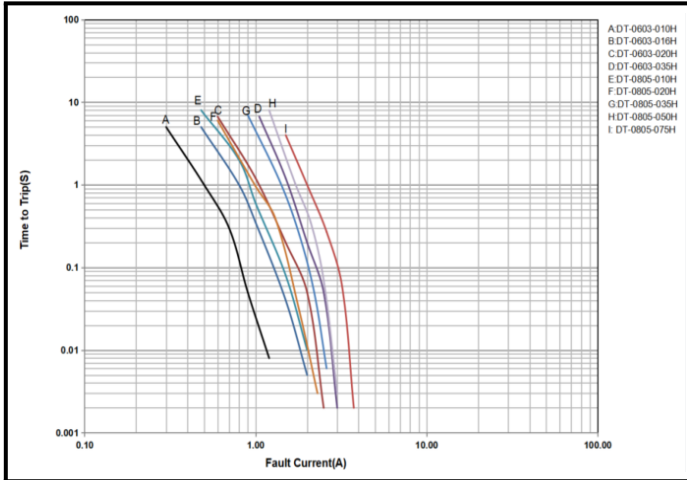


Figure 2: 1206&1210 Series

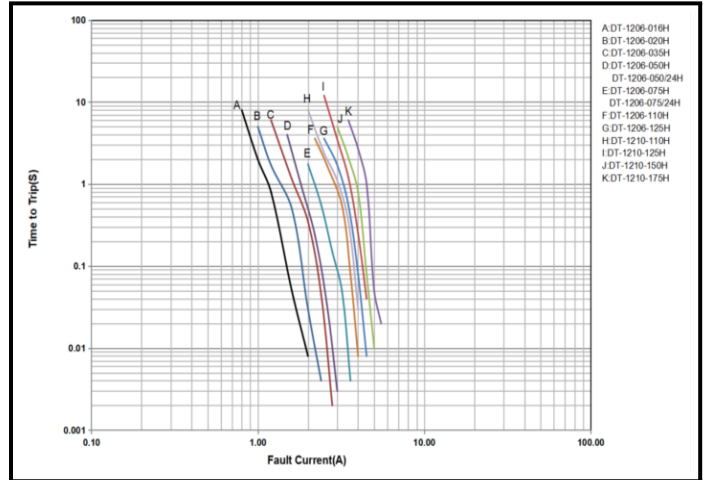
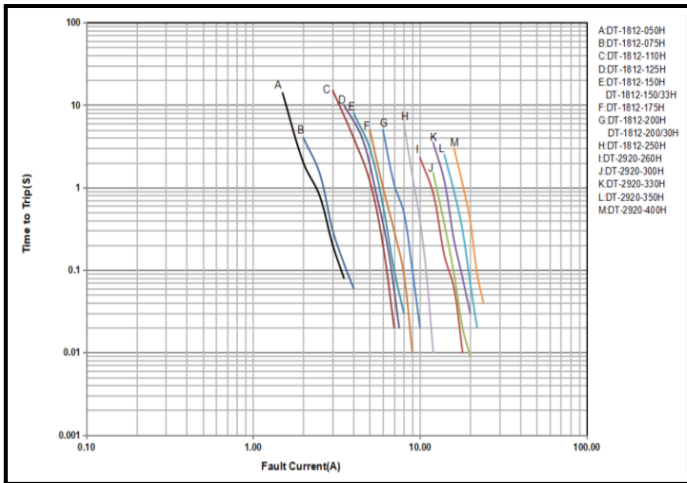
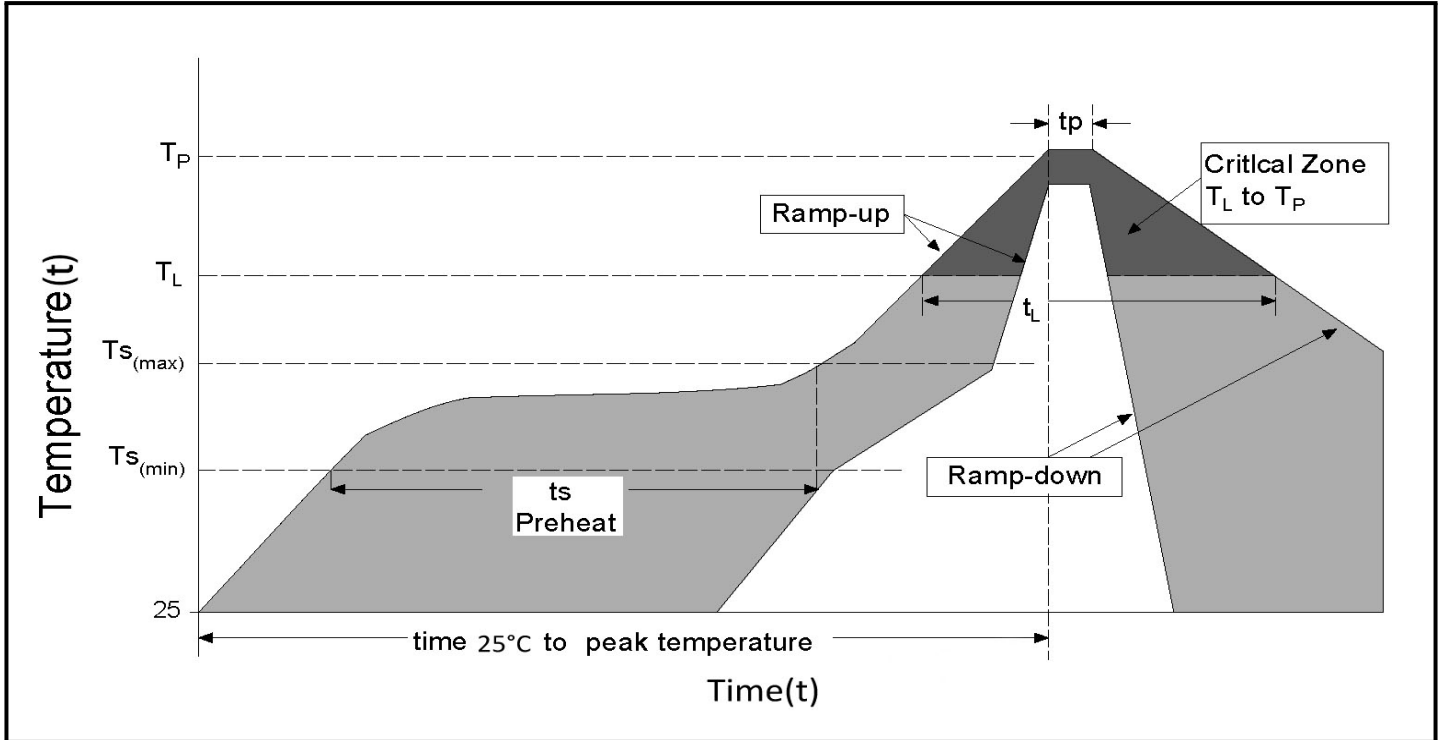


Figure 3: 1812&2920 Series



Soldering Parameters



Profile Feature		Pb-Free Assembly
Average Ramp-Up Rate ($T_{S(max)}$ to T_P)		3°C/second max
Pre Heat	Temperature Min ($T_{S(min)}$)	150°C
	Temperature Max ($T_{S(max)}$)	200°C
	Time (min to max) (t_s)	60 - 180 secs
Time Maintained Above	Temperature (T_L)	217°C
	Temperature (t_L)	60 -150 secs
Peak Temperature (T_P)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 - 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.

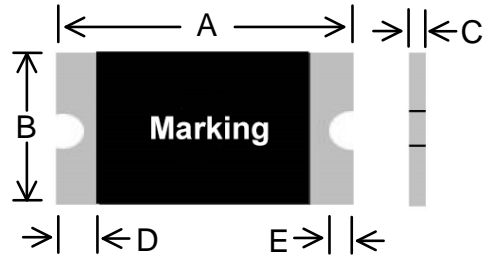
- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Recommended maximum paste thickness is 0.25mm.
- Devices can be cleaned using standard industry methods and solvents.
- All temperature refer to topside of the package, measured on the package body surface.
- If reflow temperature exceed the recommended profile, devices may not meet the performance requirements.



BxSMHxx Series

High Temperature Series
Surface Mount PPTC Devices

Product Dimensions(mm)&Marking



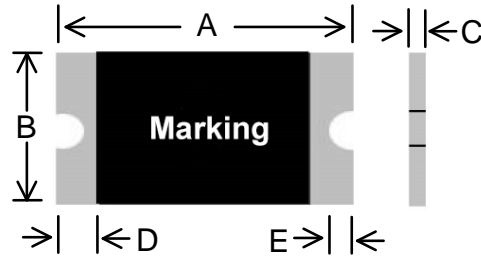
Model	A		B		C		D		E	Marking	pcs/R
	Min	Max	Min	Max	Min	Max	Min	Max	Min		
BTSMH010/24	1.45	1.85	0.65	1.05	0.4	0.8	0.15	0.5	0.05	b	4000
BTSMH016/24	1.45	1.85	0.65	1.05	0.4	0.8	0.15	0.5	0.05	d	4000
BTSMH020/16	1.45	1.85	0.65	1.05	0.4	0.8	0.15	0.5	0.05	f	4000
BTSMH035/16	1.45	1.85	0.65	1.05	0.4	0.8	0.15	0.5	0.05	h	4000
BISMH010/24	2.00	2.3	1.2	1.5	0.4	0.9	0.2	0.55	0.1	<u>1</u>	5000
BISMH020/24	2.00	2.3	1.2	1.5	0.4	0.9	0.2	0.55	0.1	<u>2</u>	5000
BISMH035/16	2.00	2.3	1.2	1.5	0.4	0.9	0.2	0.55	0.1	<u>3</u>	5000
BISMH050/16	2.00	2.3	1.2	1.5	0.4	0.9	0.2	0.55	0.1	<u>5</u>	5000
BISMH075/16	2.00	2.3	1.2	1.5	0.65	1.15	0.2	0.55	0.1	<u>7</u>	4000
BNSMH016/30	3.00	3.4	1.4	1.8	0.35	0.85	0.25	0.75	0.1	HC	5000
BNSMH020/30	3.00	3.4	1.4	1.8	0.35	0.85	0.25	0.75	0.1	H2	5000
BNSMH035/24	3.00	3.4	1.4	1.8	0.35	0.85	0.25	0.75	0.1	H3	5000
BNSMH050/16	3.00	3.4	1.4	1.8	0.35	0.85	0.25	0.75	0.1	H5	5000
BNSMH050/24	3.00	3.4	1.4	1.8	0.65	1.15	0.25	0.75	0.1	<u>H5</u>	3500
BNSMH075/16	3.00	3.4	1.4	1.8	0.35	0.85	0.25	0.75	0.1	H7	5000
BNSMH075/24	3.00	3.4	1.4	1.8	0.65	1.15	0.25	0.75	0.1	<u>H7</u>	3500
BNSMH110/16	3.00	3.4	1.4	1.8	0.65	1.15	0.25	0.75	0.1	H11	3500
BNSMH125/16	3.00	3.4	1.4	1.8	0.65	1.15	0.25	0.75	0.1	H12	3500
BFSMH110/16	3.00	3.43	2.35	2.8	0.35	0.85	0.25	0.75	0.1	DH/11	4000
BFSMH125/16	3.00	3.43	2.35	2.8	0.65	1.15	0.25	0.75	0.1	DH/12	3500
BFSMH150/16	3.00	3.43	2.35	2.8	0.65	1.15	0.25	0.75	0.1	DH/15	3500
BFSMH175/16	3.00	3.43	2.35	2.8	0.65	1.15	0.25	0.75	0.1	DH/17	3500
BMSMH050/30	4.37	4.73	3.07	3.41	0.35	0.85	0.3	1.2	0.2	DH/050	2000
BMSMH075/30	4.37	4.73	3.07	3.41	0.35	0.85	0.3	1.2	0.2	DH/075	2000
BMSMH110/24	4.37	4.73	3.07	3.41	0.65	1.15	0.3	1.2	0.2	DH/110	1500
BMSMH125/24	4.37	4.73	3.07	3.41	0.65	1.15	0.3	1.2	0.2	DH/125	1500
BMSMH150/24	4.37	4.73	3.07	3.41	0.65	1.15	0.3	1.2	0.2	DH/150	1500



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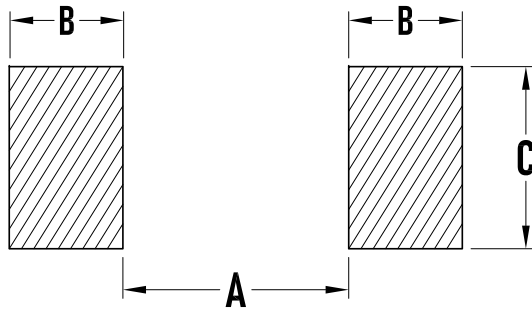
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Product Dimensions(mm)&Marking



Model	A		B		C		D		E	Marking	pcs/R
	Min	Max	Min	Max	Min	Max	Min	Max	Min		
BMSMH150/33	4.37	4.73	3.07	3.41	1.00	1.5	0.3	1.2	0.2	DH/150	1000
BMSMH175/24	4.37	4.73	3.07	3.41	0.65	1.15	0.3	1.2	0.2	DH/175	1500
BMSMH200/24	4.37	4.73	3.07	3.41	1.00	1.5	0.3	1.2	0.2	DH/200	1000
BMSMH200/30	4.37	4.73	3.07	3.41	1.00	1.5	0.3	1.2	0.2	DH/200	1000
BMSMH250/24	4.37	4.73	3.07	3.41	1.00	1.5	0.3	1.2	0.2	DH/250	1000
BSMH260/24	6.73	7.98	4.8	5.44	0.6	1.00	0.3	2.5	0.25	DH/260	1500
BSMH300/24	6.73	7.98	4.8	5.44	0.6	1.00	0.3	2.5	0.25	DH/300	1500
BSMH330/24	6.73	7.98	4.8	5.44	1.00	1.5	0.3	2.5	0.25	DH/330	1500
BSMH350/24	6.73	7.98	4.8	5.44	1.00	1.5	0.3	2.5	0.25	DH/350	1500
BSMH400/24	6.73	7.98	4.8	5.44	1.00	1.5	0.3	2.5	0.25	DH/400	1500

Recommended Pad Layout(mm) & Physical Specifications



Pad Dimensions(mm)			
Series	A	B	C
2920	4.60	2.00	5.30
1812	2.70	1.50	3.20
1210	2.00	1.00	2.80
1206	2.00	1.00	1.80
0805	1.20	1.00	1.50
0603	0.80	1.00	1.00

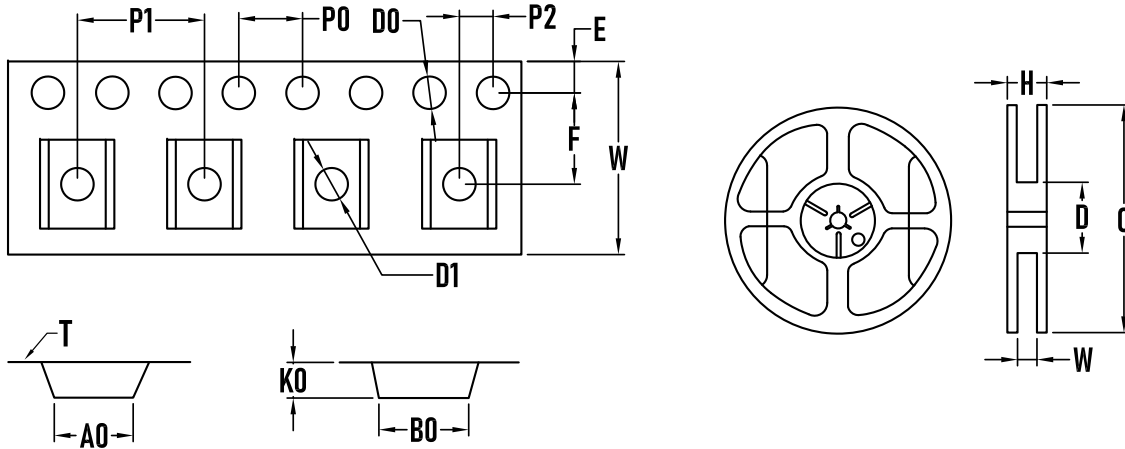
Terminal Material	Tin-Plated Nickle-Copper (Solder Material: Matte Tin (Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.



BxSMHxx Series

High Temperature Series
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Tape and Reel Specifications & Packaging quantity per Reel



TAPE SPECIFICATIONS: EIA-481-1

Item	0603	0805		1206		1210		1812			2920
W	8.00±0.30	8.00±0.10	8.10±0.10	8.10±0.10	8.10±0.10	8.10±0.10	8.10±0.10	12.0±0.10	12.0±0.10	12.0±0.10	16.00±0.30
F	3.50±0.10	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05	7.50±0.10
E1	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
D0	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05
D1	0.50±0.10	1.00 min	1.00 min	1.00 min	1.00 min	1.00 min	1.00 min	1.50 min	1.50 min	1.50 min	1.50±0.10
P0	4.00±0.10	4.0±0.10	4.0±0.10	4.0±0.10	4.0±0.10	4.0±0.10	4.0±0.10	4.0±0.10	4.0±0.10	4.0±0.10	4.0±0.10
P1	4.00±0.10	4.0±0.10	4.0±0.10	4.0±0.10	4.0±0.10	4.0±0.10	4.0±0.10	8.0±0.10	8.0±0.10	8.0±0.10	8.0±0.10
P2	2.00±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.10
A0	1.10±0.10	1.70±0.10	1.70±0.10	1.90±0.10	2.00±0.10	3.00±0.10	3.00±0.10	3.58±0.10	3.58±0.10	3.50±0.10	5.74±0.10
B0	1.90±0.10	2.45±0.10	2.45±0.10	3.45±0.10	3.50±0.10	3.50±0.10	3.50±0.10	4.93±0.10	4.93±0.10	4.90±0.10	8.02±0.10
T	0.20±0.10	0.20±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.30±0.10
K0	0.85±0.10	0.80±0.10	0.95±0.10	0.85±0.10	1.05±0.10	0.85±0.10	1.22±0.10	0.87±0.10	1.30±0.10	1.70±0.10	1.30±0.10
Leader	390mm	390mm	390mm	390mm	390mm	390mm	390mm	390mm	390mm	390mm	390mm
Trailer	160mm	160mm	160mm	160mm	160mm	160mm	160mm	160mm	160mm	160mm	160mm
Q'ty(pcs/Reel)	4000	5000	4000	4000	3500	4000	3500	2000	1500	1000	1500

REEL DIMENSIONS: EIA-481-1

Item	0603	0805	1206	1210	1812	2920
C	Ø178±1.0	Ø178±1.0	Ø178±1.0	Ø178±1.0	Ø178±1.0	Ø178±3.0
D	Ø60.2±0.5	Ø60.2±0.5	Ø60.2±0.5	Ø60.2±0.5	Ø60.2±0.5	Ø60.2±0.5
W	9.0±1.5	9.0±1.5	9.0±1.5	9.0±1.5	13.2±1.5	17.0±0.2
H	11.0±0.5	11.0±0.5	11.0±0.5	11.0±0.5	16.0±0.5	19.5±1.0





BxSMHxx Series

High Temperature Series
Surface Mount PPTC Devices

Applications Notice

- Operation of these PPTC devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire.
- These PPTC devices are intended to protect against the effects of temporary over-current or over-temperature conditions and shall not be taken for use as switch, Multiple times tripping shall lower the PPTC hold current
- Exposure to lubricants, silicon-based oils, solvents, gels, electrolytes, acids, and other related or similar materials may adversely affect the performance of PPTC devices.
- Circuits with inductance may generate a voltage above the rated voltage of the PPTC device and should be thoroughly evaluated within the user's application during the PPTC selection and qualification process.
- Please do not smash, clamp, pull, dent or twist by tool during assembling process, as they may result in the PPTC damage.
- The above parameters are concluded from one time of reflow soldering processing the PPTC. If there is any further heat generated process like injection or dispensing at the customer's premise, the aforementioned parameters will decrease at certain degree. Therefore the verification test to be conducted is necessary .
- When mounting or using PPTC, all injection molding materials, curing adhesives, UV glue , silica gel and cleaning agents or solvents must be tested in terms of application parameters e.g. temperature, time, and etc to ensure the consistency between the product and the processing before use.
- The PPTC is thermal sensitive device. It is recommended not to design any heat source devices around it to reduce the outside heat source impact.
- SMD PPTC is designed for SMT processing which applies reflow soldering. Please refer to the DTE recommended curve for reference. If the reflow soldering temperature exceeds the recommended value, the PPTC might be damaged. Hand welding PPTC is prohibited, if there is soldering iron welding process, it is suggested that the welding position should be more than 1.5mm away from PPTC, the welding tool temperature should be lower than 350℃, and the contact time between soldering iron and solder joint should not exceed 3sec.
- In charging terminal application, PP type material is recommended to use as inner membrane and TPE and PVC type material is inhibited PPTC

